

**NOFO 2: Small-Scale Supply Chain Facilities (~\$300M Capital Expenditures)**

Under the second NOFO, this application pipeline is for small-scale commercial semiconductor material and manufacturing equipment facilities below \$300 million in capital expenditures

[Change Application Pipeline](#)

Concept Plan

OMB Control Number: 0693-XXXX  
Expiration Date: XX/XX/XXXX

[View Burden Statement](#)

Acknowledgement

SECTION STATUS  
Not Started

[Get Started](#)

Cover Page and Applicant Profile

SECTION STATUS  
Not Started

[Get Started](#)

Sources and Uses of Funds

SECTION STATUS  
Not Started

[Get Started](#)

Concept Plan Project Information

SECTION STATUS  
Not Started

[Get Started](#)

Narrative Uploads

SECTION STATUS  
Not Started

[Get Started](#)

Confirm Ability to Submit a Full Application

SECTION STATUS  
Not Started

[Get Started](#)

Attestation & Submission

SECTION STATUS  
Not Started

[Get Started](#)

Submission available on  
XX/XX/XXXX

## Application Pipeline Selection

### \* Application Pipeline Selection

- NOFO 1: Front-End and Back-End Commercial Fabrication Facilities
- NOFO 1: Large-Scale Supply Chain Facilities ( $\geq$ \$300M Capital Expenditures<sup>1</sup>)
- NOFO 2: Small-Scale Supply Chain Facilities ( $<$ \$300M Capital Expenditures<sup>1</sup>)
- Other Facilities

Reminder: If your supply-chain project is at or over \$300M in **Total Capital Expenditures** you should select NOFO 1: Large-Scale Supply Chain Facilities. For more details, refer to the instructions.

- **NOFO 1: Front-End and Back-End Commercial Fabrication Facilities:** Under the first NOFO, this application pipeline is for leading-edge, current-generation, and mature-node front-end manufacturing, and back-end production facilities.
- **NOFO 1: Large-Scale Supply Chain Facilities ( $\geq$ \$300M Capital Expenditures<sup>1</sup>):** Under the first NOFO, this application pipeline is for large-scale commercial semiconductor material and manufacturing equipment facilities exceeding \$300 million in capital expenditures, as well as wafer manufacturing facilities of any size.
- **NOFO 2: Small-Scale Supply Chain Facilities ( $<$ \$300M Capital Expenditures<sup>1</sup>):** Under the second NOFO, this application pipeline is for small-scale commercial semiconductor material and manufacturing equipment facilities below \$300 million in capital expenditures.
- **Other Facilities:** The last application pipeline is for other all facility types that are not covered in the first three categories.

You may change this selection at any time until the full application submission.

<sup>1</sup>Project capital expenditures refers to expenses incurred in the construction or improvement of physical assets, such as the costs of land, building and construction, equipment and installation, physical improvements, and working capital during the construction phase.

Next

## Steps

- Application Pipeline Selection

## Burden Statement

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A Federal agency may not conduct or sponsor, and a person is not required to respond to, nor shall a person be subject to a penalty for failure to comply with an information collection subject to the requirements of the Paperwork Reduction Act of 1995 unless the information collection has a currently valid OMB Control Number. The approved OMB Control Number for this information collection is 0693-XXXX. Without this approval, we could not conduct this information collection. Public reporting for this information collection is estimated to be approximately 30 minutes per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the information collection. All responses to this information collection are required to obtain benefits. Send comments regarding this burden estimate or any other aspect of this information collection, including suggestions for reducing this burden to the National Institute of Standards and Technology at: [askchips@chips.gov](mailto:askchips@chips.gov).

## Acknowledgement

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Any communication, data, or other information stored or transmitted on this system may be accessed and used by federal employees, consultants and contractors in accordance with Section IV.C. of the CHIPS Incentives Program – Facilities for Semiconductor Materials and Manufacturing Equipment (CHIPS-CFF SMME-01). By voluntarily furnishing information through this system, the applicant consents to such access and use.

I acknowledge the above statement

Next

## Cover Page

### View Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Facilities for Semiconductor Materials and Manufacturing Equipment, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Complete the CHIPS Program Cover Page questions with the following information regarding the proposed application. Instructions for how to complete the form are located here: <https://www.nist.gov/document/XXXXXX>.

Be sure to include any statements regarding the confidentiality of information contained within the Concept Plan application, in accordance with Section IV.C of the NOFO.

Name of Application

### Potential Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Concept Plan.

Potential Applicant Name (e.g., applying entity)

Corporate Parent Name

Street 1

Street 2

Country/Area

City

International State

Postal C...

Organization Website

Have you registered for a SAM.gov account?

Response

-- Clear --

Yes

No

Save and  
Next

## Steps

- Cover Page
- Cover Page

## Cover Page

### Applicant Point of Contact

Please enter information for the applicant point of contact, who should be an individual authorized to submit an application on behalf of the entity.

First Name	<input type="text"/>	Last Name	<input type="text"/>
Title	<input type="text"/>	Phone Number	<input type="text"/>
		Email Address	<input type="text"/>

### Additional Applicant Details

Please list all primary officers (first name, last name, title)

First Name	Last Name	Title

Is the global headquarters address the same as the organization address?

\* Response

**Global Headquarters Address**

\* Street 2

\* Country/Area   \* City   \* International State

    

\* Posta...

Select the applicant organization ownership structure

List all shareholders with >5% total equity (If none, then write 'N/A')

List all countries of operations

#### Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

## Steps

- Cover Page and Applicant Profile
- Cover Page**

Previous

Finish

## Cover Page

### Applicant Point of Contact

Please enter information for the applicant point of contact, who should be an individual authorized to submit an application on behalf of the entity.

First Name	<input type="text"/>	Last Name	<input type="text"/>
Title	<input type="text"/>	Phone Number	<input type="text"/>
		Email Address	<input type="text"/>

### Additional Applicant Details

Please list all primary officers (first name, last name, title)

First Name	Last Name	Title

Is the global headquarters address the same as the organization address?

\* Response

### Global Headquarters Address

\* Street 1

\* Street 2

\* Country/Area  \* City  \* International State

\* Posta...

Select the applicant organization ownership structure

-- Clear --

Public

Private

List all countries or operations

### Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

\*

## Steps

- Cover Page and Applicant Profile
- Cover Page**

Previous

Finish

## Uses of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

### Schedule A: Summation Across Projects – Cost Schedule (\$ USD)

1. Capital Investment	\$ 4,590,000.00
1a. Land	\$ 2,500,000
1b. Construction Costs (Labor, Materials)	\$ 1,000,000
1c. Equipment	\$ 500,000
1d. Infrastructure Improvements (Utility Plants, Access to Infrastructure, Wastewater Treatment)	\$ 500,000
1e. Administrative Expenses directly attributable to the construction, expansion, or modernization (Legal, engineering, permitting fees)	\$ 30,000
1f. Other Capital Investment	\$ 60,000
2. Other Uses of Funds	\$ 45,000
Total Project Costs	\$ 4,635,000.00

Next

## Steps

- Uses of Funds Form
- Sources of Funds Form

## Uses of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

### Schedule A: Summation Across Projects – Cost Schedule (\$ USD)

1. Capital Investment	\$ 540,000.00
1a. Land	\$ 250,000
1b. Construction Costs (Labor, Materials)	\$ 100,000
1c. Equipment	\$ 50,000
1d. Infrastructure Improvements (Utility Plants, Access to Infrastructure, Wastewater Treatment)	\$ 50,000
1e. Administrative Expenses directly attributable to the construction, expansion, or modernization (Legal, engineering, permitting fees)	\$ 30,000
1f. Other Capital Investment	\$ 60,000
2. Other Uses of Funds	\$ 45,000
Total Project Costs	\$ 585,000.00

Please make sure your units for your request is not in Thousands or Millions

Next

## Steps

- Uses of Funds Form
- Sources of Funds Form



## Uses of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

### Schedule A: Summation Across Projects – Cost Schedule (\$ USD)

1. Capital Investment

\$ 2,510,640,000.00

**NOFO 2 is only for supply chain projects with capital expenditures below \$300M. With the current proposed capital expenditure, this project is not eligible for this NOFO. Please apply under NOFO 1 for supply chain projects at or above \$300M in capital investment.**

1a. Land

\$ 2,500,000,000

1b. Construction Costs (Labor, Materials)

\$ 10,000,000

1c. Equipment

\$ 500,000

1d. Infrastructure Improvements (Utility Plants, Access to Infrastructure, Wastewater Treatment)

\$ 50,000

1e. Administrative Expenses directly attributable to the construction, expansion, or modernization (Legal, engineering, permitting fees)

\$ 30,000

1f. Other Capital Investment

\$ 60,000

2. Other Uses of Funds

\$ 45,000

Total Project Costs

\$ 2,510,685,000.00

Next

## Steps

**Uses of Funds Form**

Sources of Funds Form

# Sources of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

## Schedule B: Summation Across Projects – Sources Schedule (\$ USD)

<b>1. Equity Funding</b>	\$ 500,000.00
1a. Sponsor Equity (Applicant and/or Corporate Parent)	\$ 500,000
1b. Third-Party Equity	\$ 0
1c. Other Equity Funding	\$ 0
<b>2. Debt Funding</b>	\$ 3,000,000.00
2a. Sponsor Debt	\$ 3,000,000
2b. Third-Party Debt (e.g., Bonds or Loans)	\$ 0
2c. Other Debt Funding	\$ 0
<b>3. Government Support</b>	\$ 620,000.00
3a. Anticipated CHIPS Direct Funding Request	\$ 500,000
<b>Please make sure your units for your request is not in Thousands or Millions</b>	
3b. Investment Tax Credit (estimated)	\$ 120,000
3c. State and Local Government Incentives (Grants + Loans + Tax Credits)	\$ 0
<b>4. Other Sources of Funds</b>	\$ 0
<b>Total Project Funding</b>	\$ 4,120,000.00

The request for CHIPS funding exceeds 10% of project capital expenditures. Please provide your CHIPS Incentives Justification with a particular focus on (1) how your project advances economic and national security objectives and (2) why the additional funding is necessary to make the project commercially viable.

Please explain why your project's total costs exceed total sources of funds

## Steps

Uses of Funds Form



Sources of Funds Form

# Sources of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

## Schedule B: Summation Across Projects – Sources Schedule (\$ USD)

<b>1. Equity Funding</b>	<input type="text" value="\$ 50,000,000.00"/>
1a. Sponsor Equity (Applicant and/or Corporate Parent)	<input type="text" value="\$ 50,000,000"/>
1b. Third-Party Equity	<input type="text" value="\$ 0"/>
1c. Other Equity Funding	<input type="text" value="\$ 0"/>
<b>2. Debt Funding</b>	<input type="text" value="\$ 3,000,000.00"/>
2a. Sponsor Debt	<input type="text" value="\$ 3,000,000"/>
2b. Third-Party Debt (e.g., Bonds or Loans)	<input type="text" value="\$ 0"/>
2c. Other Debt Funding	<input type="text" value="\$ 0"/>
<b>3. Government Support</b>	<input type="text" value="\$ 620,000.00"/>
3a. Anticipated CHIPS Direct Funding Request	<input type="text" value="\$ 500,000"/>
<b>Please make sure your units for your request is not in Thousands or Millions</b>	
3b. Investment Tax Credit (estimated)	<input type="text" value="\$ 120,000"/>
3c. State and Local Government Incentives (Grants + Loans + Tax Credits)	<input type="text" value="\$ 0"/>
<b>4. Other Sources of Funds</b>	<input type="text" value="\$ 0"/>
<b>Total Project Funding</b>	<input type="text" value="\$ 53,620,000.00"/>

Provide your CHIPS Incentives Justification

Previous

Next

## Steps

Uses of Funds Form



Sources of Funds Form

## Consortium and Partner Information

Is the applicant a part of a consortium?

\* Response

Yes

Has anyone from the consortium already applied?

\* Response

No

You will be given a Consortium Key on the following screen. Please share this key with your Consortium partners to use in their application. Describe your consortium partners.

Consortium Title

ABC Group

Consortium Description

Group of Consorts

### Partnering Entities, if applicable

Are there other entities (e.g. customers, suppliers, investors, advisor(s) you anticipate partnering with in a meaningful way?

\* Response

Yes

Please describe any potential partners referred to above. (max. 1500 characters)

\* Response

This is a description of potential partners - separate from Consortium

Next

## Steps

- Consortium and Partner Information
- Project(s) Information
- Facilities Information
- Facility Outputs

## Consortium and Partner Information

Is the applicant a part of a consortium?

\* Response

No

### Partnering Entities, if applicable

Are there other entities (e.g. customers, suppliers, investors, advisor(s) you anticipate partnering with in a meaningful way?

\* Response

No

Next

### Steps

- Consortium and Partner Information
- Project(s) Information
- Facilities Information
- Facility Outputs

## Project(s) Information

### Consortium Details

Consortium? Yes

Consortium Id: ed21b22b-7266-aabb-9411-6aab1a380fa1

Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

#### Site Location

City

Danbury

State

Connecticut

ZIP Code

06811-0000

Site location not yet known

Previous

Next

### Steps

- Consortium and Partner Information
- Project(s) Information
- Facilities Information
- Facility Outputs

## Consortium and Partner Information

Is the applicant a part of a consortium?

\* Response

Yes

Has anyone from the consortium already applied?

\* Response

Yes

Please provide the Consortium Key. This was generated when another member of the Consortium applied.

Consortium Key

ed21b22b-7268-aabb-9411-6aab1a360fa1

## Partnering Entities, if applicable

Are there other entities (e.g. customers, suppliers, investors, advisor(s) you anticipate partnering with in a meaningful way?

\* Response

Yes

Please describe any potential partners referred to above. (max. 1500 characters)

\* Response

This is a description of potential partners - separate from Consortium

Next

## Steps

- Consortium and Partner Information
- Project(s) Information
- Facilities Information
- Facility Outputs

## Facilities Information

Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

According to the NOFO, an application may include one project, a set of capital expenditures for the construction, expansion, or modernization of a single facility.

Name

Project Type

Facility Type

Project Start

Production Start

Expected Total Capital Exp...

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## Steps

Consortium and Partner Information

Project(s) Information

**Facilities Information**

Facility Outputs

## Facilities Information

Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

According to the NOFO, an application may include one project, a set of capital expenditures for the construction, expansion, or modernization of a single facility.

Name

Project Type

-- Clear --

Construction of New Facility

Expansion or Modernization of Existing ...

Facility Type

Production Start

Expected Total Capital Expenditures for...

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## Steps

Consortium and Partner Information

Project(s) Information

**Facilities Information**

Facility Outputs

## Facilities Information

Instructions for how to complete these questions are located here: <https://www.nist.gov/xyz>

According to the NOFO, an application may include one project, a set of capital expenditures for the construction, expansion, or modernization of a single facility.

Name

Project Type  Facility Type

Project Start  Production  -- Clear --  Total Expenditures for...

Semiconductor Materials Facilities  
Semiconductor Manufacturing Equipme...

## Steps

- Consortium and Partner Information
- Project(s) Information
- Facilities Information**
- Facility Outputs



# Facility Outputs

Name	Project Type	Facility Type	Number of Materials / Equipment Produced
Facility 1	Construction of New Facility	Semiconductor Materials Facility	2

  

**EQUIPMENT**

Equipment Type	Peak Monthly Capacity	Unit of Production	Cost per Unit of Production	Projected Price per Unit
Deposition	100	Widget A	\$2.50	\$12.00

**MATERIALS**

Material Type	Peak Monthly Capacity	Unit of Production	Cost per Unit of Production	Projected Price per Unit
wafers	200	Widget B	\$100.50	\$12.00

**Enter Equipment Details**

Equipment Type:

If Type = Other:

Other Type:

Peak Monthly Capacity:

Unit Of Production:

Cost per Unit of Production:

Projected Price per Unit:

If Type = Other:

Other Type:

**Enter Material Details**

Material Type:

If Type = Other:

Other Type:

Material Details:

If Material Details = Other - Other Description:

Specific Material:

Material Uses:

If Type = Other:

Other Type:

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## Steps

- Consortium and Partner Information
- Project(s) Information
- Facilities Information
- Facility Outputs**

Name	Project Type	Facility Type	Number of Materials / Equipment Produced
Facility 1	Construction of New Facility	Semiconductor Materials Facility	2

**EQUIPMENT**

Equipment Type	Peak Monthly Capacity	Unit of Production	Cost per Unit of Production	Projected Price per Unit
Deposition	100	Widget A	\$2.50	\$12.00

**MATERIALS**

Material Type	Peak Monthly Capacity	Unit of Production	Cost per Unit of Production	Projected Price per Unit
wafers	200	Widget B	\$100.50	\$12.00

**Enter Equipment Details**

Equipment Type:

If Type = Other:

Other Type:

Peak Monthly Capacity:

Unit Of Production:

Cost per Unit of Production:

Projected Price per Unit:

**Enter Material Details**

Material Type:

If Type = Other:

Other Type:

Material Details:

If Material Details = Other - Other Description:

Specific Material:

Peak Monthly Capacity:

Unit Of Production:

Cost per Unit of Production:

Projected Price per Unit:

Material Uses:

**Enter Equipment Details**

Equipment Type:

If Type = Other:

Other Type:

Peak Monthly Capacity:

Unit Of Production:

Cost per Unit of Production:

Projected Price per Unit:

**Enter Material Details**

Material Type:

If Type = Other:

Other Type:

Material Details:

If Material Details = Other - Other Description:

Specific Material:

Peak Monthly Capacity:

Unit Of Production:

Cost per Unit of Production:

Projected Price per Unit:

Material Uses:

## Consortium Narrative

### View Confidentiality Statement

Submit a PDF attachment that provides a consortium narrative of no more than 5 pages. For complete details on the Consortium Narrative, please refer to the instructions ([link here](#)). The consortium narrative must include the following information, and each member is responsible for ensuring consistency across all related applications:

1. The individual entities that are members or proposed members of the consortium and the roles of each entity
2. A narrative description of the consortium's overall strategic vision: how that vision aligns with the Department's economic and national security objectives; and the relevance of each proposed project to that vision
  - a. Include an explanation of why the proposed projects are necessary to advance the consortium's vision, and why CHIPS funding is necessary to incentivize the relevant investment
  - b. For consortia that include a state and/or local government (including quasi-governmental) entity, this narrative should also list any actions that entity is taking or intends to take to facilitate cluster development, such as efforts to coordinate with suppliers on site selection, infrastructure development, workforce development, permitting, and/or community engagement
3. The structure of the consortium, including how members intend to coordinate and/or collaborate with one another

Required Upload – 1 pdf of Consortium Narrative of no more than 5 pages indicating confidential pages in accordance with Section IV.G.2 of the NOFO

Upload

 Or drop files

FileName	Upload Date
----------	-------------

Next

## Steps

- Consortium Narrative
- Concept Plan Narrative

# Concept Plan Narrative

## View Confidentiality Statement

Submit a PDF attachment that provides a concept plan of no more than 15 pages. The concept plan should describe the project for which CHIPS Incentives funds are being requested. The description of the project(s) should be responsive to the program description (see section I of the NOFO) and the Evaluation Criteria (see section V.A of the NOFO). Attachments such as the Project Sources and Uses of Funds spreadsheet are not included in this page limit. For complete details on the Concept Plan Narrative, please refer to the instructions (link here). The concept plan must contain the following information and document sections:

1. Table of Contents
2. Description of Project
3. Applicant Profile
4. CHIPS Incentives Justification
5. Economic and National Security Details
6. Commercial Viability Details
7. Project Feasibility and Readiness Details
8. Availability of Funds Details (Includes Capital Investment and Project Capital Sources)

Required Upload – 1 pdf of Concept Plan of no more than 15 pages indicating confidential pages in accordance with Section IV.C.2 of the NOFO

Upload

Or drop files

FileName	Upload Date	
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Optional Upload – Please include supporting documents including a cover page containing a legend for confidential information in accordance with Section IV.C.2 of the NOFO

Upload

Or drop files

FileName	Upload Date	
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## Steps

Consortium Narrative

**Concept Plan Narrative**

## Eligibility Question

For the full application, will you be able to provide evidence of your eligibility for CHIPS Incentives funds with respect to the project for which you are submitting an application? For more details on the statutory eligibility requirements, refer to Section III on (add link to instructions or NOFO 2 documentation here when available)

- i. Are you a "covered entity," meaning a nonprofit entity, a private entity, a consortium of private entities, or a consortium of nonprofit, public, and private entities with a demonstrated ability to substantially finance, construct, expand, or modernize a facility relating to materials used to manufacture semiconductors or semiconductor manufacturing equipment?
- ii. Do you have a documented interest in constructing, expanding, or modernizing an eligible facility?
- iii. Have you been offered a covered incentive from a state or local jurisdiction?
- iv. Have you made commitments to worker and community investment?
- v. Have you secured commitments from regional education and training entities and institutions of higher education to provide workforce training?
- vi. Do you have an executable plan to sustain the facility without additional funding from the CHIPS incentives Program?
- vii. Have you documented your workforce needs and produced a strategy to meet such workforce needs?
- viii. Have you determined the types of semiconductor equipment and/or materials you will produce at the proposed facility, and the customers, or categories of customers, to whom the items will be sold?
- ix. Do you have an executable plan to identify and mitigate relevant semiconductor supply chain security risks, such as risks associated with access, availability, confidentiality, integrity, and a lack of geographic diversification in your supply chain?

Response

-- Clear --

Yes

No

Concept Plan submission)

interest:  
sortium with other applicants, you may work  
statutory eligibility and other requirements  
be provided for the full application (not this

## Steps

- Eligibility Question

Save  
and  
Finish

## Eligibility Question

For the full application, will you be able to provide evidence of your eligibility for CHIPS Incentives funds with respect to the project for which you are submitting an application? For more details on the statutory eligibility requirements, refer to Section III on (add link to instructions or NOFO 2 documentation here when available)

- i. Are you a "covered entity," meaning a nonprofit entity, a private entity, a consortium of private entities, or a consortium of nonprofit, public, and private entities with a demonstrated ability to substantially finance, construct, expand, or modernize a facility relating to materials used to manufacture semiconductors or semiconductor manufacturing equipment?
- ii. Do you have a documented interest in constructing, expanding, or modernizing an eligible facility?
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- iv. Have you made commitments to worker and community investment?
- v. Have you secured commitments from regional education and training entities and institutions of higher education to provide workforce training?
- vi. Do you have an executable plan to sustain the facility without additional funding from the CHIPS incentives Program?
- vii. Have you documented your workforce needs and produced a strategy to meet such workforce needs?
- viii. Have you determined the types of semiconductor equipment and/or materials you will produce at the proposed facility, and the customers, or categories of customers, to whom the items will be sold?
- ix. Do you have an executable plan to identify and mitigate relevant semiconductor supply chain security risks, such as risks associated with access, availability, confidentiality, integrity, and a lack of geographic diversification in your supply chain?

Response

To note regarding documented interest:

- i. If applying as part of a consortium with other applicants, you may work together to satisfy various statutory eligibility and other requirements
- ii. These details will need to be provided for the full application (not this Concept Plan submission)

Save  
and  
Finish

## Steps

○ Eligibility Question

## Attest and Submit

The CHIPS Program Office (CPO) recognizes the importance of protecting confidential business information and will follow all applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C of the CHIPS Incentives Program - Facilities for Semiconductor Materials and Manufacturing Equipment Notice of Funding Opportunity (CHIPS-SMME-01 NOFO) for a further discussion of these laws

### Submission Certifications

Attestation
The individual submitting the Application certifies on behalf of the applicant entity that the applicant information and data submitted and the representations made in the Application are true, complete and accurate, to the best of the applicant's knowledge and belief after due inquiry.
<input type="checkbox"/>

Attestation
The individual submitting the Application certifies on behalf of the applicant that the applicant understands that CPO and the Department of Commerce will rely on the accuracy and completeness of the applicant information and data submitted and the representations made in the Application and that any false, fictitious or fraudulent statement or representation made in the Application may be the basis for rejection of the Application or subject the applicant to criminal, civil, or administrative penalties. (16 U.S. Code, Section 1001.)
<input type="checkbox"/>

Attestation
The individual submitting the Application certifies on behalf of the applicant that the applicant understands that any applicant information and data contained in the Application may be accessed and used by federal employees, consultants and contractors in accordance with CHIPS-SMME-01 NOFO, Section IV.C. (Confidential Information).
<input type="checkbox"/>

Attestation
The individual submitting the Application certifies that they possess the full legal power and authority to submit the Application and make the preceding certifications on behalf of the applicant.
<input type="checkbox"/>

Attestation
The individual submitting the Application agrees that neither the applicant entity nor any of its affiliates may issue any press release or otherwise publicly disclose the status of the Application or the contents of any communications with CPO or the Department of Commerce without CPO's prior written consent.
<input type="checkbox"/>

Attestation
The individual submitting the Concept Plan certifies that they possess the full legal power and authority to bind the applicant.
<input type="checkbox"/>

Company Name  
Title  
Applicant Name

Next

## Steps

Attest and Submit

